

## **IMAPS Global Business Council**

Spring Conference, March 16 & 17, 2008 (as of March 1st)  
Ft. McDowell Radisson Resort, Scottsdale, AZ

### **Title of event/focus area:**

“Addressing Cost and Performance Driven Semiconductor Packaging Challenges through the Supply Chain.”

- ❖ What are the specific areas where assembly and packing cost needs to be addressed to enable the growth of the industry?
- ❖ Where are the applications where performance rather than cost is the absolute driver?
- ❖ What and where are the opportunities within the supply chain to meet these challenges and how many companies benefit from providing solutions?

### **Chairs of the GBC Spring Conference:**

Howard Imhof, Metalor Technologies USA, Director of Sales and Marketing  
Greg Caswell, Vice President, Sales and Marketing, D2M Technologies

### **Session Chairs of the GBC Spring Conference:**

Gary Nicholls, OEM Marketing Manager, Cookson Electronics  
Lee Smith, Senior Director of Business Development, Amkor Technology, Inc.

### **Sunday, March 16**

GBC Golf Outing. 12:00 We-ko-pa Golf Course at the Ft. McDowell Radisson.  
Registration Opens and Welcome Reception with light appetizers. 6:00 PM

### **Monday, March 17**

Registration opens 7:00 AM.  
Continental breakfast from 7:15 – 8:00 AM  
Program starts at 8:00 AM.  
Lunch is at 12:00 Noon.  
Program adjourns at 5:00 PM.

### **Opening Remarks and Keynote Address – 8:00 AM:**

Opening Remarks by  
Howard Imhof, Chair of the IMAPS Global Business Council  
Director of Sales and Marketing, Metalor Technologies USA

Keynote address by

Bill Bottoms

Chief Executive Officer, NanoNexus

“The 10th Anniversary Edition of the International Technology Roadmap for Semiconductors.”

**Microelectronics Industry Overview; 9:00 AM – 10:30:**

9:00 "Packaging the Supply Chain."  
Jim Walker, Vice President Research, Gartner/Dataquest

9:40 Coffee Break

9:50 "The Role of Precious Metals in Electronics & the Semiconductor Supply Chain - Past, Present, & Future." Conor Dullaghan, Vice President, Sales & Marketing, Metalor Technologies Advanced Coatings Division

10:30 "How M&A Activities Are Affecting the Supply Chain in the Electronic Packaging Industry." Loren Lancaster, Managing Director, Core Capital, Electronics and Semiconductor Group

**Cost Driven Challenges; 11:10 PM – 1:40 PM:**

11:10 "How Do Materials and Process Suppliers Enable Next-generation Semiconductor Packaging While Addressing Ever Increasing Cost Pressures?"  
Steven J. Corbett, Chief Executive Officer, Cookson Electronics.

**12:00 Lunch**

1:00 "Package Optimization for Cost Driven Applications."  
Lee Smith, Sr. Director, Business Development, Amkor Technology, Inc.

**Performance Driven Challenges; 1:40 PM – 3:50 PM:**

1:40 "Common Platform Alliance for Semiconductor Packaging Technology."  
Scottie Ginn, Vice President of Design Enablement and Packaging, IBM Systems and Technology Group

2:20 "Challenges for Adopting Standard IC Packaging Solutions for High Reliability Medical Applications." Robert Erich, Component Development Engineer, Medtronic Microelectronics Center

3:00 Coffee Break

3:10 "High Reliability Microelectronics Packaging for Military & Avionic Applications."  
Mark Dimke, Engineering Manager, Microelectronics Packaging, Sensor Systems, Rockwell Collins.

**Electronics Packaging in China; 3:50 PM – 4:50 PM:**

3:50 "The Development of Semiconductor Packaging and Testing Industry of China"  
Prof. Bi Keyun, President of China Electronics Packaging Society

4:50 Closing Remarks and Adjourn

5:00 – 7:00 Device Packaging Welcome Reception (beverages and light appetizers)  
GBC Spring Conference Attendees Invited